

## ULTRASONIC BONDING

ACCESSORIES 4.305

APPLICATIONS: SMT

ZEVAC LINE: ONYX 29



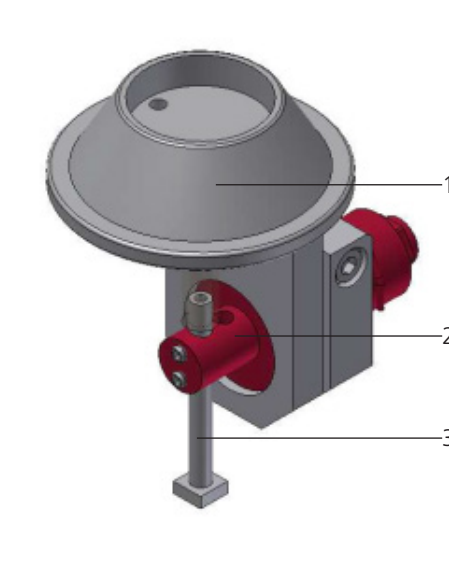
The option Ultrasonic Bonding for components in the semiconductor industry, developed for the semi-automatic platform ONYX 29, includes the ultrasonic generator and the transducer (resonator).

The 8-bit digital ultrasonic generator UUG-050/B by F&K Physiktechnik operates with a frequency range of 40 to 150kHz with a maximum power of 12.5W.

The relevant parameters time, power, force and temperature can be entered directly in the ONYX software VisualMachines. The frequency is determined and controlled by the ultrasonic generator.

A constant bonding process results from a repeatable resonance frequency of the bonding tool, which can only be achieved with a stable fixture of the transducer and the bonding tool. The transducer FK090Z by F&K Physiktechnik, with a resonance frequency of 90kHz, is clamped in an adapter which is mounted at the machine head using the standard nozzle cone. The screws for mounting the transducer and the bonding tool are torqued with a specific force.

The bonding tool / vacuum nozzle is connected to the nozzle vacuum, so the components can be picked, aligned using the vision unit and placed prior to the bonding process without tool change.



- 1 Transducer-adapter with ONYX standard nozzle cone
- 2 Transducer
- 3 Bonding tool / Vacuum nozzle

Technical Data Subject to Change

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